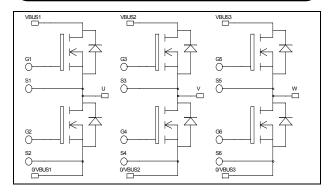


Triple phase leg Super Junction MOSFET Power Module



$$\begin{split} V_{DSS} &= 600V \\ R_{DSon} &= 35 m\Omega \text{ max } @ \text{ Tj} = 25^{\circ}\text{C} \\ I_D &= 72 \text{A} @ \text{Tc} = 25^{\circ}\text{C} \end{split}$$

Application

- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies
- Motor control

Features



Power Semiconductors

- Ultra low R_{DSon}
- Low Miller capacitance
- Ultra low gate charge
- Avalanche energy rated
- Very rugged
- Kelvin source for easy drive
- Very low stray inductance
 - Symmetrical design
 - Lead frames for power connections
- High level of integration



- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Very low (12mm) profile
- Each leg can be easily paralleled to achieve a phase leg of three times the current capability
- Module can be configured as a three phase bridge
- Module can be configured as a boost followed by a full bridge
- RoHS Compliant

	VBUS1	VBUS2	VBUS3
	G1 ●S1	. G3 ®S3	G5 S5
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	U (EXE)	V (=======)	*

Absolute maximum ratings

Symbol	Parameter		Max ratings	Unit
$V_{ m DSS}$	Drain - Source Breakdown Voltage		600	V
T	Continuous Drain Current	$T_c = 25^{\circ}C$	72	
I_{D}	Continuous Diam Current	$T_c = 80$ °C	54	Α
I_{DM}	Pulsed Drain current		200	
V_{GS}	Gate - Source Voltage		±20	V
R_{DSon}	Drain - Source ON Resistance		35	$m\Omega$
P_{D}	Maximum Power Dissipation $T_c = 25^{\circ}C$		416	W
I_{AR}	Avalanche current (repetitive and non repetitive)		20	A
E_{AR}	Repetitive Avalanche Energy		1	T
E_{AS}	Single Pulse Avalanche Energy		1800	mJ

😭 🛦 🕬 📆 These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.



All ratings @ $T_j = 25$ °C unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0V, V_{DS} = 600V$ $T_j = 25^{\circ}C$			40	μА
		$V_{GS} = 0V, V_{DS} = 600V$ $T_j = 125^{\circ}C$			375	
R _{DS(on)}	Drain – Source on Resistance	$V_{GS} = 10V, I_D = 72A$			35	mΩ
V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 5.4 \text{mA}$		3	3.9	V
I_{GSS}	Gate – Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±150	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Тур	Max	Unit
C _{iss}	Input Capacitance	$V_{GS} = 0V$		14		
C_{oss}	Output Capacitance	$V_{DS} = 25V$		5.13		nF
C_{rss}	Reverse Transfer Capacitance	f = 1MHz		0.42		
Q_{g}	Total gate Charge	$V_{GS} = 10V$		518		
Q_{gs}	Gate – Source Charge	$V_{\text{Bus}} = 300V$		58		nC
Q_{gd}	Gate – Drain Charge	$I_D = 72A$		222		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching @ 125°C		21		
$T_{\rm r}$	Rise Time	$\begin{aligned} V_{GS} &= 15V \\ V_{Bus} &= 400V \\ I_D &= 72A \\ R_G &= 2.5\Omega \end{aligned}$		30		
$T_{d(off)}$	Turn-off Delay Time			283		ns
T_{f}	Fall Time			84		
Eon	Turn-on Switching Energy	Inductive switching @ 25°C		1340		T
E_{off}	Turn-off Switching Energy	$V_{GS} = 15V, V_{Bus} = 400V$ $I_D = 72A, R_G = 2.5\Omega$		1960		μJ
E_{on}	Turn-on Switching Energy	Inductive switching @ 125°C		2192		T
E _{off}	Turn-off Switching Energy	$V_{GS} = 15V, V_{Bus} = 400V$ $I_D = 72A, R_G = 2.5\Omega$		2412		μJ

Source - Drain diode ratings and characteristics

Source Drain aroue racings and characteristics							
Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
I_S	Continuous Source current		$Tc = 25^{\circ}C$		72		۸
	(Body diode)		$Tc = 80^{\circ}C$		54		Α
V_{SD}	Diode Forward Voltage	$V_{GS} = 0V, I_S = -72A$				1.2	V
dv/dt	Peak Diode Recovery •					6	V/ns
t _{rr}	Reverse Recovery Time	$I_S = -72A$	$T_j = 25^{\circ}C$		580		ns
Q_{rr}	Reverse Recovery Charge	$V_R = 350V$ $di_S/dt = 200A/\mu s$	$T_j = 25^{\circ}C$		46		μС

• dv/dt numbers reflect the limitations of the circuit rather than the device itself.

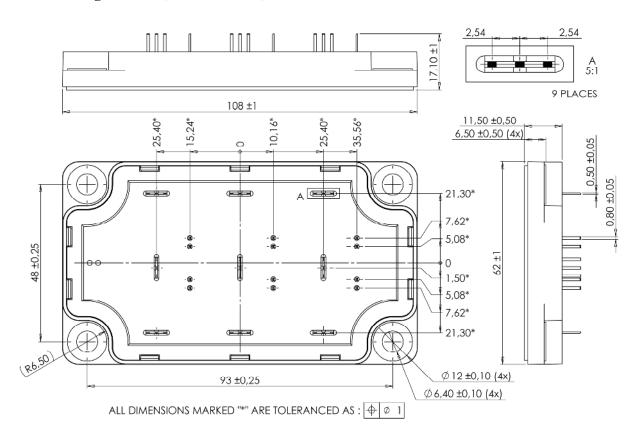
 $I_S \le$ - 72A $di/dt \le 200 A/\mu s$ $V_R \le V_{DSS}$ $T_j \le 150 ^{\circ} C$



Thermal and package characteristics

Symbol	Characteristic		Min	Тур	Max	Unit	
R_{thJC}	Junction to Case Thermal Resistance				0.3	°C/W	
V_{ISOL}	RMS Isolation Voltage, any terminal to case t = 1 min, 50/60Hz			4000			V
T_{J}	Operating junction temperature range		-40		150		
T_{STG}	Storage Temperature Range		-40		125	°C	
$T_{\rm C}$	Operating Case Temperature			-40		100	
Torque	Mounting torque	To heatsink	M6	3		5	N.m
Wt	Package Weight					250	g

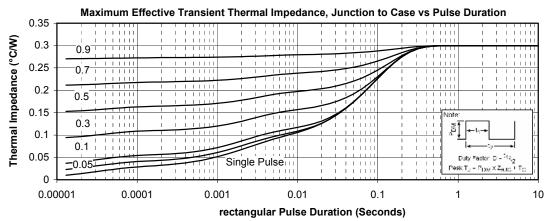
SP6-P Package outline (dimensions in mm)

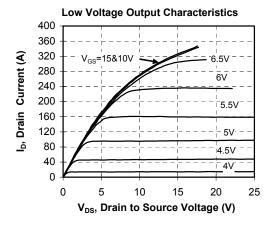


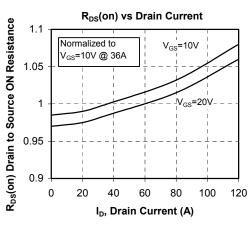
See application note 1902 - Mounting Instructions for SP6-P (12mm) Power Modules on www.microsemi.com

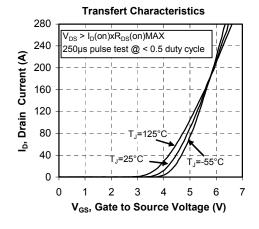


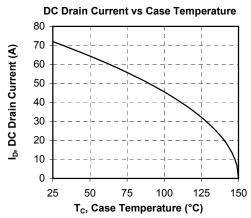
Typical Performance Curve





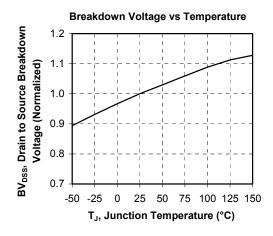


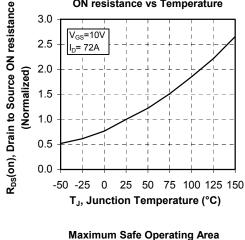


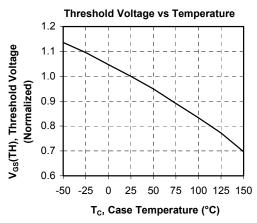


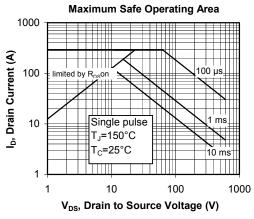


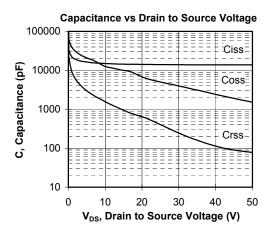
ON resistance vs Temperature

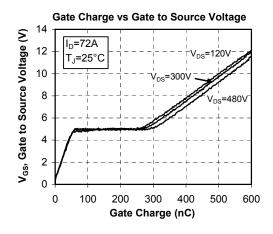




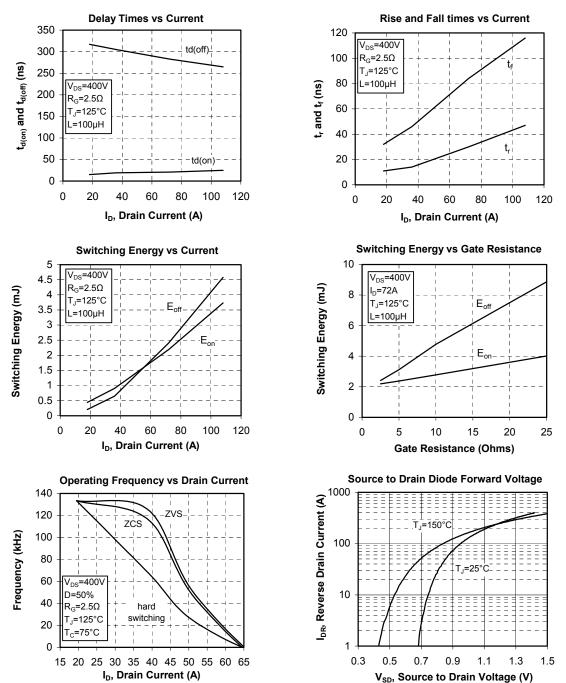












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